

**DECLARATION FOR PATENT APPLICATION/POWER
OF ATTORNEY**

As a below named inventor, I hereby declare that:

My residence, mailing address, and citizenship are as stated below next to my name. I believe I am the original, first and sole inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled: **DIE-FIRST MULTI-CHIP MODULES AND METHODS OF MANUFACTURE**, the specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56.

POWER OF ATTORNEY: As a named inventor, I (we) hereby appoint:

**Alan D. Kamrath (Reg. No. 28,227)
Hans I. Sun (Reg. No. 38,714)
Emil Moffa (Reg. No. 35,617)
Rider Bennett, Egan & Arundel, LLP
333 South Seventh Street, Suite 2000
Minneapolis, Minnesota 55402
(612) 340-8925**

as my attorney(s) or agent(s), with full process of substitution and revocation, to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full Name of Sole or First Inventor: Wendy Lee Wilkins	
Residence: 1741 Royal Court, Eau Claire, WI 54701	
Mailing Address: 1741 Royal Court, Eau Claire, WI 54701	
Country: USA	Citizenship USA
Inventor's Signature: <i>Wendy L Wilkins</i>	Date: November 5, 2003